

EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR
ENCAPSULATION AND SEMICONDUCTOR DEVICE

[ABSTRACT]

A highly reliable semiconductor device with the improved humidity resistance reliability is disclosed. A disclosed epoxy resin composition for semiconductor encapsulation encapsulates, in the manufacture of the semiconductor device, a
5 semiconductor element that is mounted on a lead frame having a die pad unit or a circuit substrate and a wire that connects an electrical junction disposed on the lead frame or circuit substrate and an electrode pad disposed on the semiconductor element. The epoxy resin composition includes an epoxy resin (A), a curing agent (B), and an inorganic filler (C). The epoxy resin (A) has a main peak area of 90% or more with respect to the total
10 area of all peaks as measured by the gel permeation chromatography area method.

FIG.1 accompanies the Abstract